



Brandenburg
University of Technology
Cottbus - Senftenberg



Prof. Harald Schenk | October 10th, 2023

Microelectronics and microsensor research at Brandenburg University of Technology Cottbus- Senftenberg (BTU C-S)

Agenda

I. Importance of microelectronics and microsensors

II. Activities at BTU C-S

- Overview
- Example projects
 - iCampus
 - OASYS

III. Activities of non-university R&D partners (RTOs) in Cottbus

- Ferdinand-Braun-Institut fuer Hoechstfrequenztechnik (FBH)
- Leibniz Institute for High Performance Microelectronics (IHP)
- Fraunhofer IPMS
- Fraunhofer IZM
- Research Fab Microelectronics Germany (FMD)

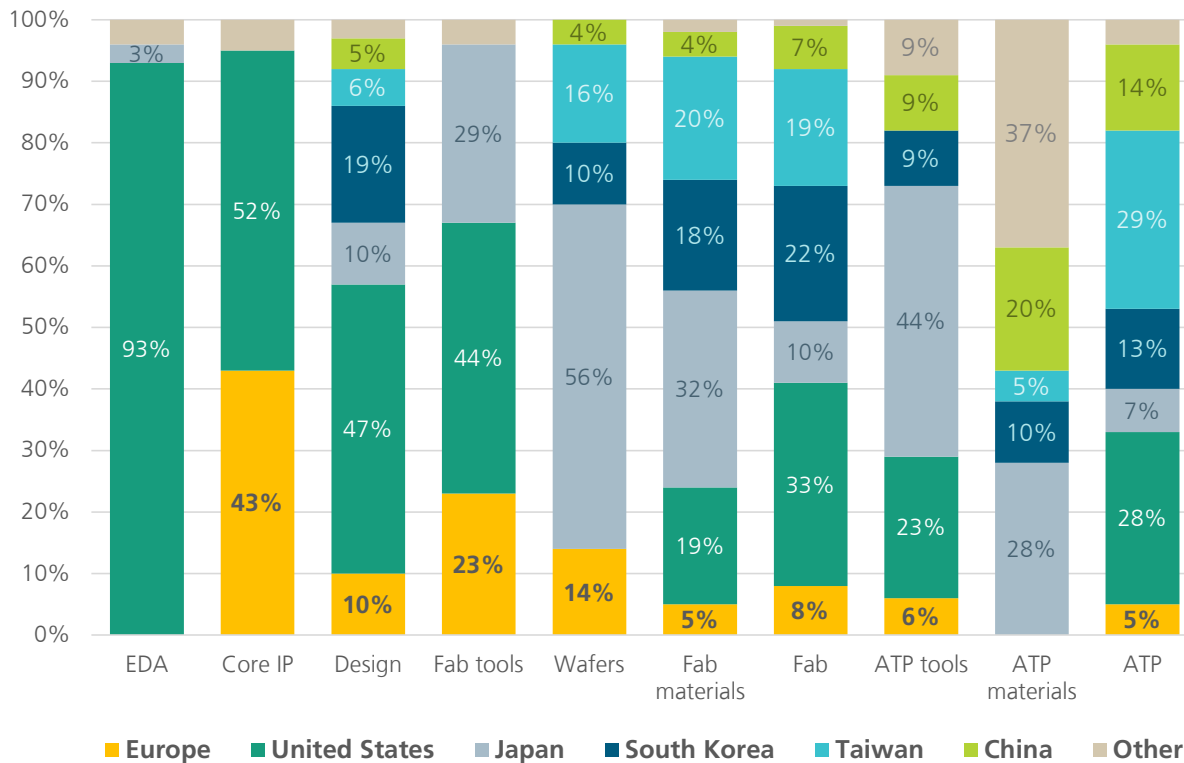


Part I

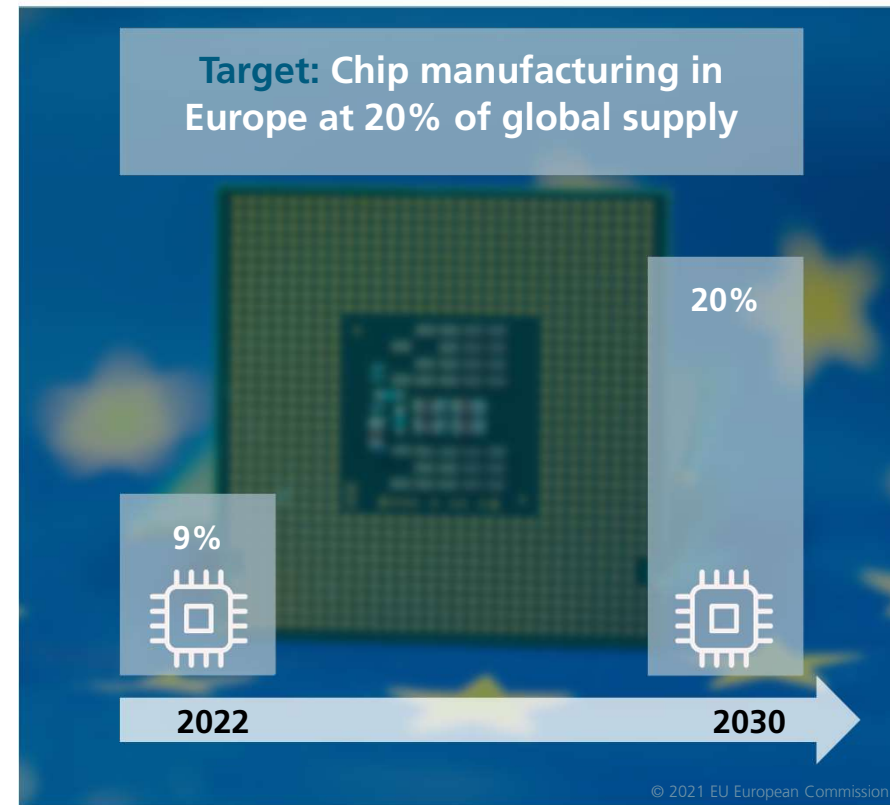
Importance of microelectronics and microsensors

Microelectronics - enabler and driver of digitization

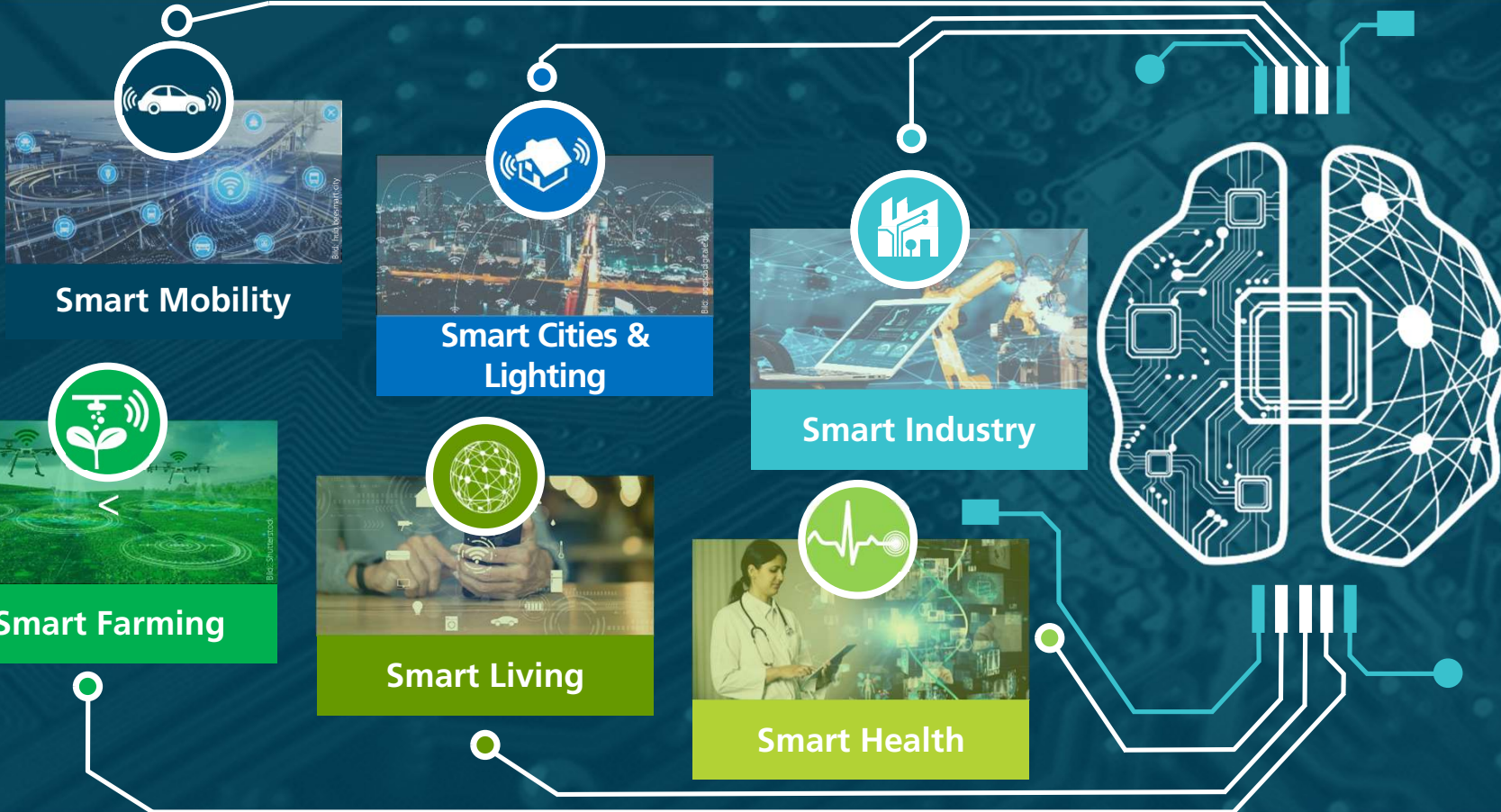
Europe's market share and ambition



Source: Kearney, 2021.
 EDA = Electronic design automation, Core IP = Core intellectual property blocks; ATP = Assembly, testing, and packaging



Microelectronics - enabler and driver of digitization



Very **high** demand for **microelectronic/microsensor solutions** in numerous and **diverse** application areas

Part II

Activities at BTU C-S

Microelectronics and Microsensorics at BTU C-S

Interdisciplinary research and development



Institute of Physics

Applied Physics and Semiconductor Spectroscopy (Prof. Flege)

Experimental Physics and Functional Materials (Prof. Fischer)

Semiconductor Materials (Prof. Wenger) 

Micro and Nano Systems 
(Prof. Schenk)


Circuit Design (Prof. Weger)


Computational Physics (Prof. Seibold)



Institute of Computer Science

Computer Engineering
(Substitute Prof. Reichenbach)

Wireless Systems 
(Prof. Langendörfer)


Distributed Measurement Systems and Sensor Networks 
(N.N. – ongoing appointment process: in review phase)





Institute of Electrical Engineering and Information Science

Electronic Systems and Sensors
(Prof. Gardill)

Microelectronics (Prof. Killat)

Semiconductor Techn. (Prof. Kahmen) 

Antennas and High-Frequency System Integration (Prof. Ndip) 

Radio Frequency and Microwave Techniques (Prof. Rudolph) 



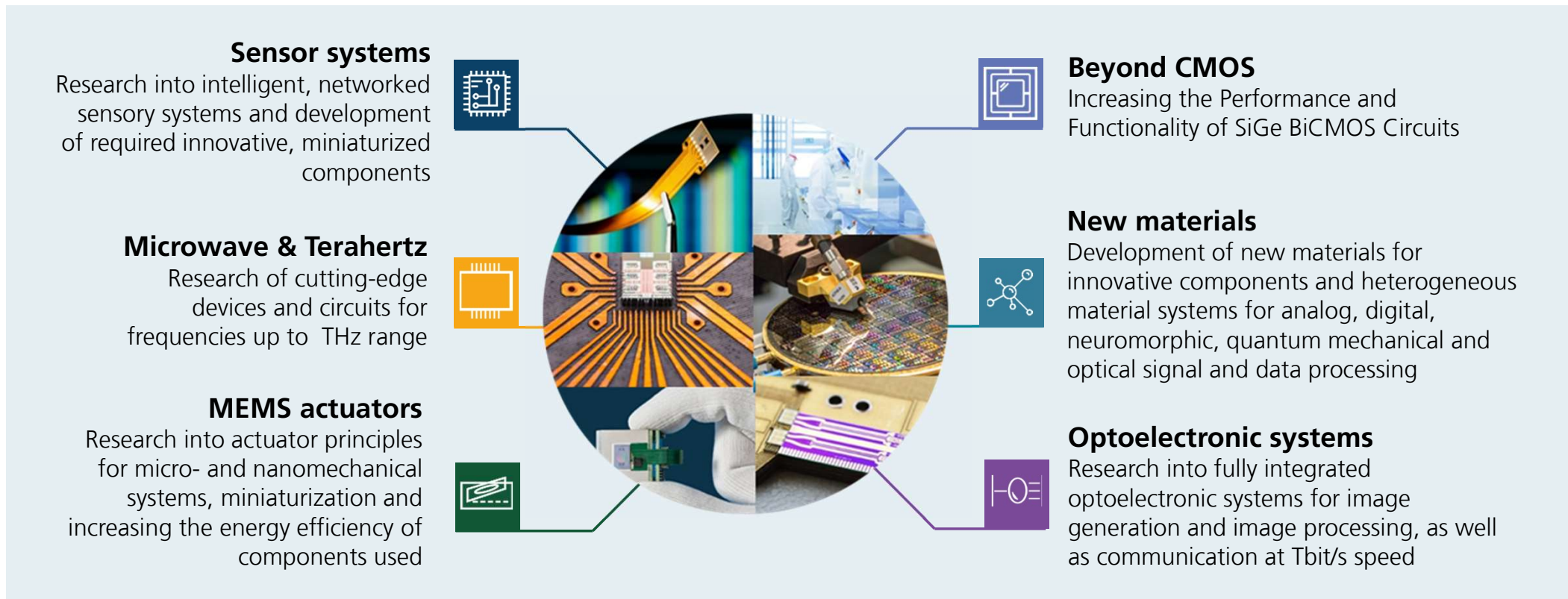
Institute of Digital Production Quality and Logistics

Automation Technology
(Prof. Berger)

   = joint appointment of BTU C-S and respective RTO

Microelectronics and Microsensorics at BTU C-S

Subject areas and bundling of competencies



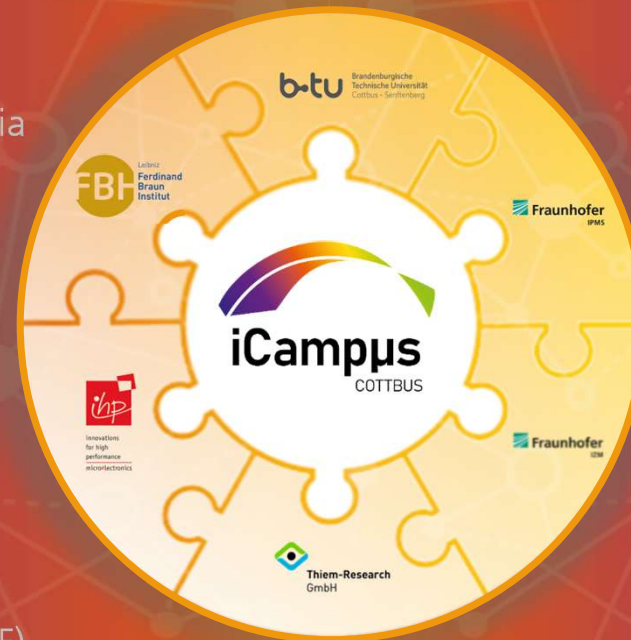
iCampus Cottbus



Innovation Campus Electronics and Microsensors Cottbus – iCampus

Research cooperation within the framework of the Federal Government for structural change in the coalmining region of Lusatia

Purpose:	R&D and transfer in the field of sensor technologies
Phase I:	11/2019 – 12/2021 5 consortium partners Volume: 7,5 M€
Phase II:	01/2022 – 12/2026 6 consortium partners (<i>new: Thiem-Research GmbH</i>) Volume: 20 M€
Funding:	Federal Ministry of Education and Research (BMBF)



Associated partners:



iCampus Cottbus – Phase II

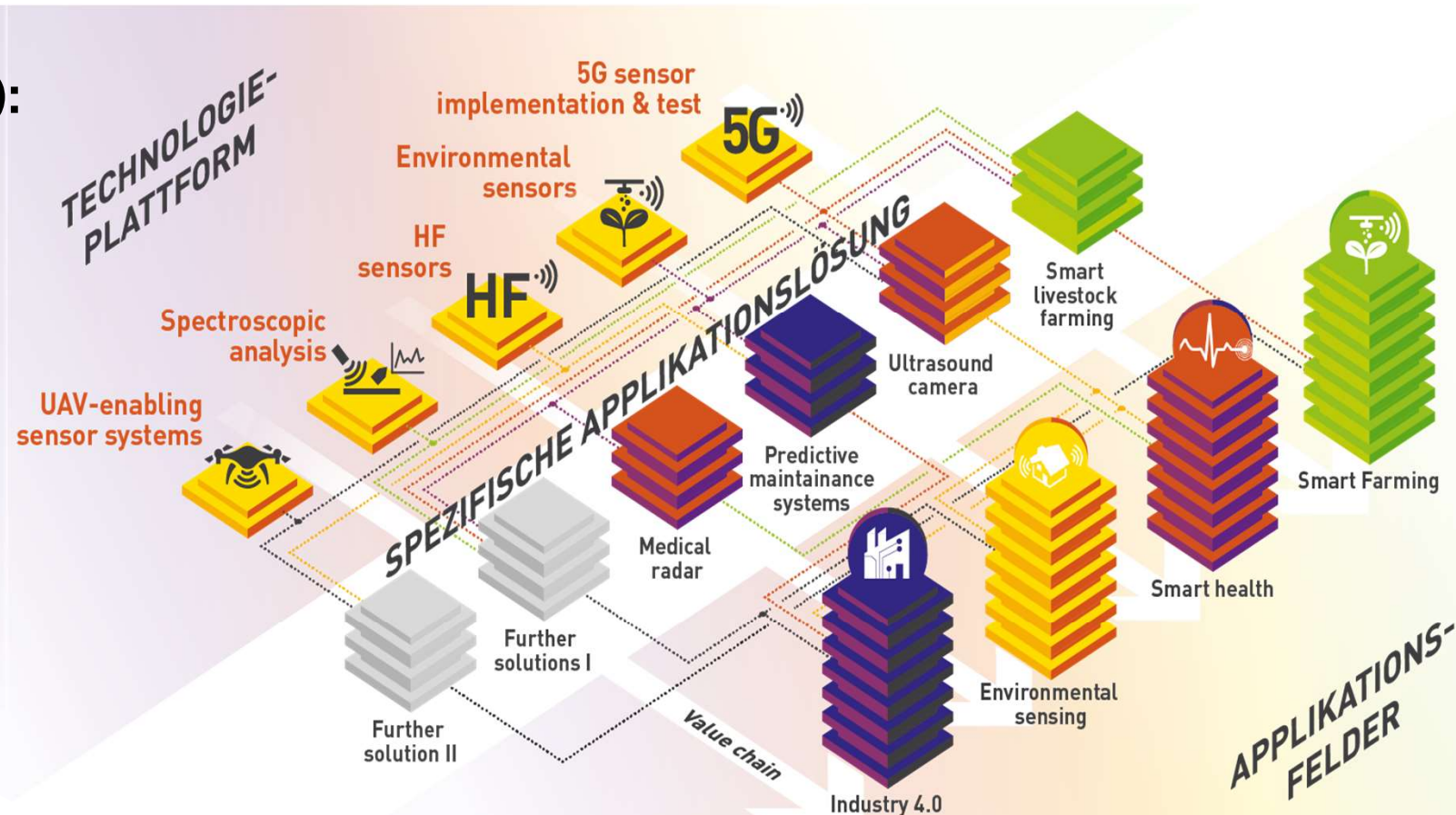
Technology platforms and special solutions



Phase II (2022-2026):

In the project,

- 5 technology platforms and
- 4 specific application solutions are developed,
- which address 4 application fields



iCampus Cottbus

iCCC2024 – iCampus-Cottbus Conference

www.iCCC2024.de



Topics:

- Actuators
- Condition monitoring
- Energy Management
- Health
- HF-MEMS
- Communication
- Lab on Chip
- Material & Process Technologies
- Mobility
- Environmental Sensors
- Economy & Sustainability



Extended Deadline for Abstracts:
November, 15th 2023

Notification of authors:
December, 1st 2023

Deadline for manuscripts:
January, 31st 2024



We look forward to your contribution!

The iCCC2024 is an event of the BMBF funded structural change project iCampus Cottbus www.iCampus-Cottbus.de. It is organized by the Innovation Team and supported by AMA GmbH.

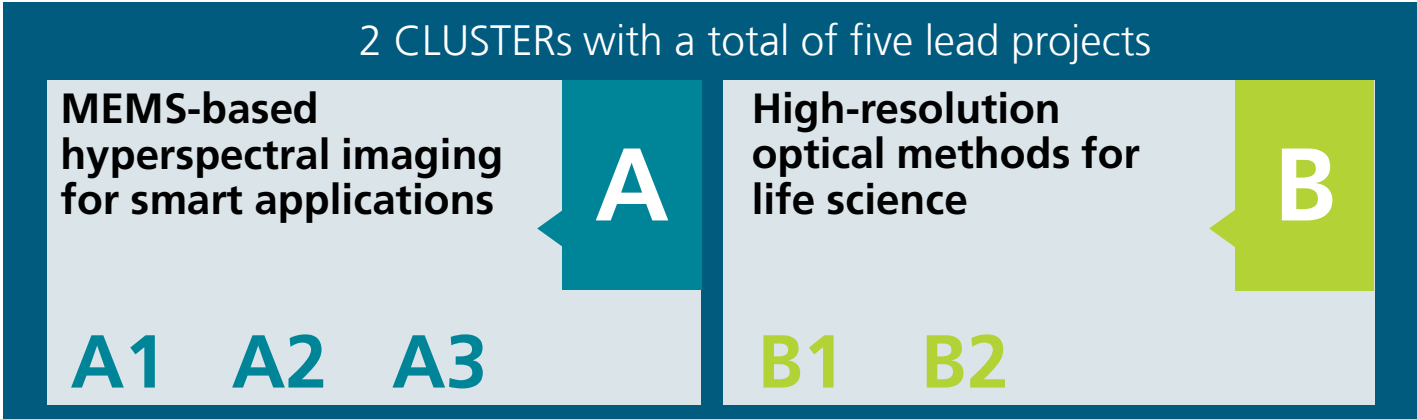
OASYS

Structure – Duration – Partner



OASYS – Optosensors for **A**dvanced **S**ystems in Life Science and Smart Production

Duration: 09/2023-09/2027 | Volume: ~ 12,5 M€
Funding: Federal Ministry of Education and Research (BMBF)



Consortium partners:



Practice partners:



OASYS

Lead projects



A

CLUSTER A » MEMS-based hyperspectral imaging for smart applications«

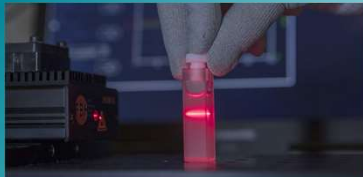
Ultra compact intelligent hyperspectral camera



Hyperspektrale Bildgebung am Beispiel eines Apfels



Imaging Spectrometer-Free Hyperspectral Raman Sensing



Si-compatible detectors for object identification applications



B

CLUSTER B » High-resolution optical methods for life science«

MEMS-based imaging in & through scattering media



Optoacoustic sensor technology



Part III

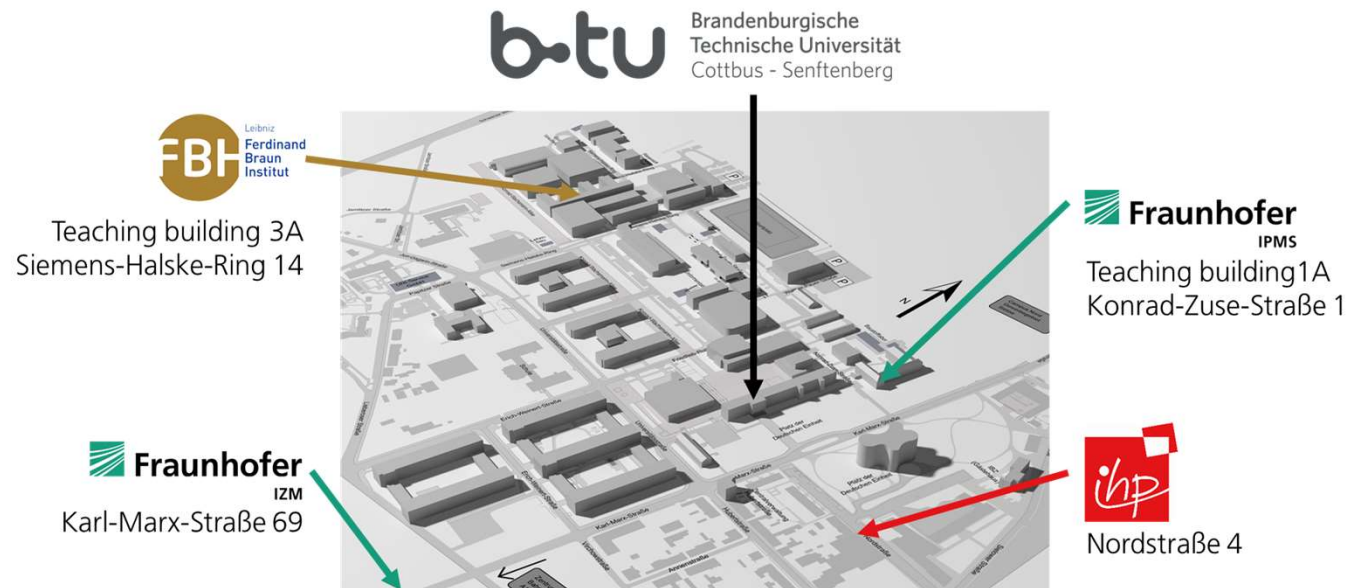
Activities of non-university R&D partners (RTOs) in Cottbus

Cooperation with non-university research institutions

Microelectronics-RTO (Research and Technology Organisation) at BTU Cottbus-Senftenberg

Extensive cooperation:

- 1 **Joint appointments**
- 2 Operation of **Joint Labs** and Fraunhofer **project groups**
- 3 Joint **R&D consortium projects**
- 4 RTO **presence on campus** with own institute or teaching building



Map of the central campus of BTU Cottbus-Senftenberg including the location of the non-university research institutions.

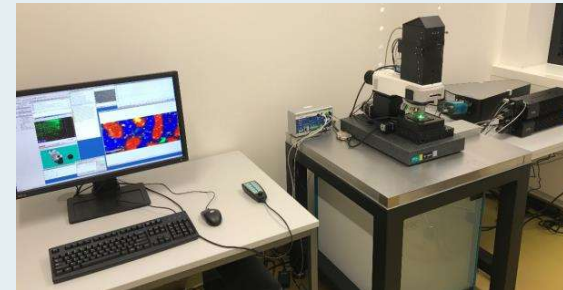
Ferdinand-Braun-Institut fuer Hoechstfrequenztechnik (FBH)

Raman Analytic for life sciences at Cottbus



Competences and Research Foci

- **Application lab:** Raman-microscope for spatially resolved measurements
- **Raman measurement systems for the medical applications**
 - Spectrometer based system with an excitation wavelength at 488 nm.
 - Spectrometer free system with an excitation wavelength at 450 nm
- **Customized light sources and turnkey systems**
- **Systems ethics approved for clinical study** together with Thiem-Research and Carl-Thiem-Clinical-Center
- **Raman measurement systems for various applications, e.g. agriculture:**
 - Spectrometer based system with an excitation wavelength near 785 nm
- Cooperation with BTU Cottbus towards the application of **artificial intelligence for data analysis**

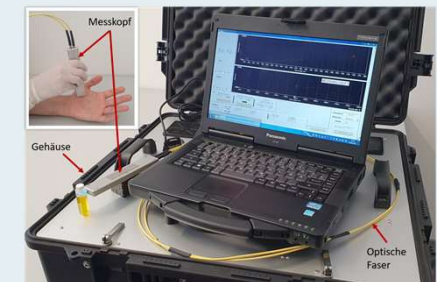


Cottbus Application Lab



Application Example: Medical Health

Raman Measurement System



Application Example: Agriculture



Leibniz Institute for High Performance Microelectronics (IHP)

Competence Center for Silicon-Germanium Technologies and Systems



R&D Services

- Qualified end-to-end SiGe BiCMOS Technologies for prototyping and small scale manufacturing
- MPW service for prototyping
- Technology development service for dedicated process steps
- RF and digital Circuit Design and IP development
- Low volume Analog, Digital- and Mixed-Signal Chip production test
- Semiconductor material analysis and failure mode analysis & diagnostics
- RF characterization and measurement support up to 500 GHz

Application-specific research and development in the following research fields:



Fraunhofer Institute for Photonic Microsystems IPMS

Branch Integrated Silicon Systems ISS



State-of-the-art research on semiconductor based photonic, electrochemical and acoustic applications

R&D Services on 200 mm and 300 mm

- **Detection** and **intelligent processing** of measured variables from miniaturized sensors and systems
- Determination of **material states** and **relevant attributes** for
 - industrial processes,
 - biological-medical diagnostics and analytics
 - and other customer specific applications
- Development of **customer-specific components, modules** and **entire systems**
- Competencies in hardware-related software development for **sensor signal processing**

Technologies: Sensors and Actuators

Artificial Intelligence

A graphic showing a hand holding a glowing blue sphere with a network of nodes and lines, representing artificial intelligence.

Ultrasonic sensors

A graphic showing a 3D perspective of a rectangular ultrasonic sensor chip with several small components on its surface.


Photonic systems

(e.g. Near-Infrared Spectroscopy)

A graphic showing a smartphone with a green sensor component attached to its back, representing photonic systems.

Chemical Sensors

(e.g. electrochemical chips, ISFET, (L)OFET)

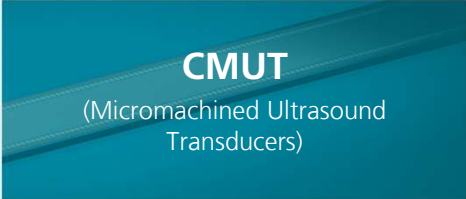
A graphic showing a close-up of a small, square chemical sensor chip with a circular electrode on its surface.

Nanosopic Electrostatic Drives (NED)

A graphic showing several blue, rectangular microchips with intricate patterns on their surfaces, representing nanoscopic electrostatic drives.

CMUT

(Micromachined Ultrasound Transducers)

A graphic showing a blue, rectangular microchip with a grid of small square elements on its surface, representing a micromachined ultrasound transducer.

Fraunhofer Institute for Reliability and Microintegration IZM

Branch Lab for High-Frequency Sensors & High-Speed Systems

Innovative RF packaging solutions, components & modules for sensing, communication & computing

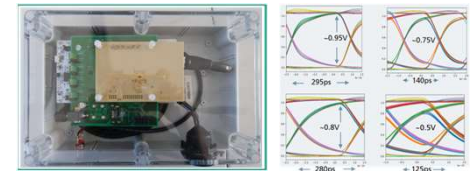
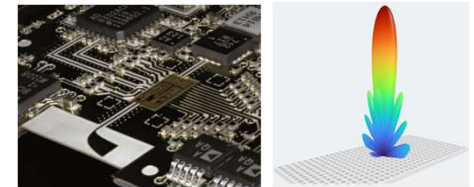
Research Fields

Application-specific research and development in the following fields:

- **Radar & proximity sensors** for
 - Medical & healthcare
 - Industrial automation
 - Safety & security
 - Smart farming
- **High-speed wireless communication** modules of end devices and systems (5G, 6G)
- **High performance computing (HPC)** modules

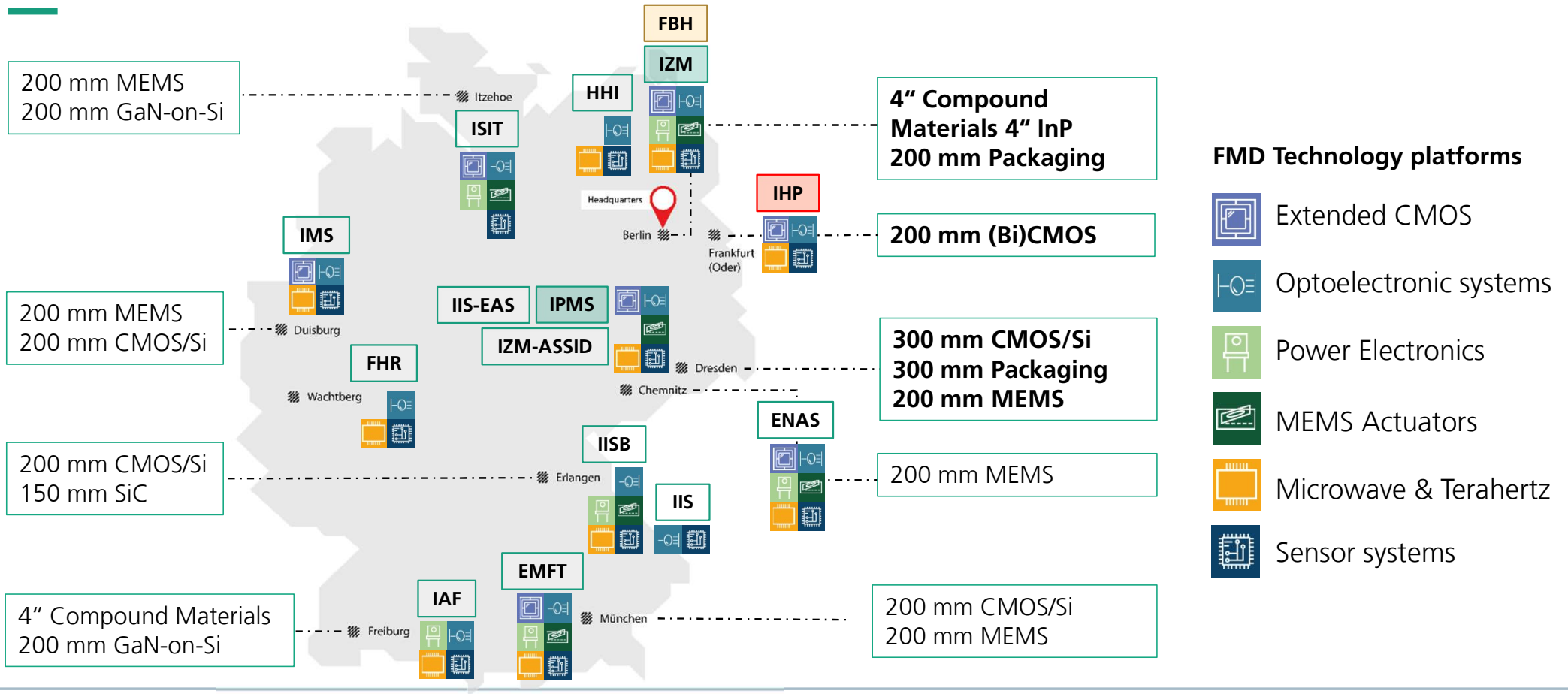
R&D Services

- **Investigation of suitable RF packaging technologies** for development of radar & proximity sensors, wireless communication and HPC modules
- **RF design, layout and measurement-based characterization** (up to 300 GHz) of the following:
 - RF front-end modules for radar sensors & communication systems (e.g. for 5G, 6G)
 - Proximity sensors (e.g. inductive sensors)
 - Antennas and passive components
 - RF packages & platforms (e.g. SiP, AiP)
- **Signal & power integrity driven design, layout and test** of high-speed interposers & boards for HPC



Research Fab Microelectronics Germany (FMD)

Clean rooms and technology platforms (Germany-wide)



Research Fab Microelectronics Germany (FMD)

One-Stop-Shop

As a **One-Stop-Shop**, FMD offers industry and science **customized technology and system developments** along the entire value chain **from a single source**.



A **single institute** with specific know-how and excellent individual competencies.

A strong cooperation of **13 institutes** with know-how and infrastructure bundled in a **One-Stop-Shop**



FMD consolidates microelectronics research spread across eleven Fraunhofer and two Leibniz institutes (FBH, IHP) in Germany



Cross-technology and **cross-institutional R&D concepts** for optimal collaboration with industry



Customized technology and system developments



Joint laboratories and joint production facilities



Organization of combined prototype and pilot production



Industrial contract research, support for innovators and start-up activities



Technology and knowledge transfer

Profile of FMD as RTO:



Applied research with a solid foundation in academic research and strong ties to industry



Focus on **heterogeneous system integration (AHSI)** in good synergy (with imec / leti) at EU level.



FMD drives research on the integration of heterogeneous systems at EU level



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Thank you very much for
your attention!
